

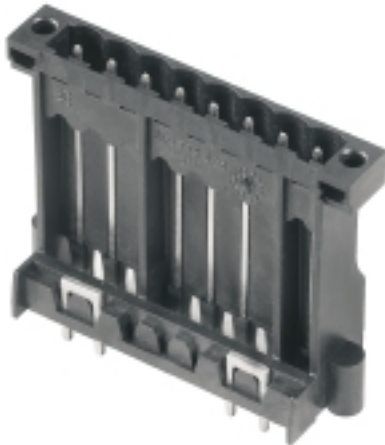
SLH-THR5.08/16/180F 3.2SN BK BX**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

Product image

Similar to illustration

Extra-high temperature-resistant male header, optimised for the SMT process. Makes a compact 3-row male header when used together with the SLDV-THR.

General ordering data

Version	PCB plug-in connector, male header, Flange, THT/THR solder connection, 5.08 mm, Number of poles: 16, 180°, Solder pin length (l): 3.2 mm, tinned, black, Box
Order No.	1190600000
Type	SLH-THR5.08/16/180F 3.2SN BK BX
GTIN (EAN)	4032248973415
Qty.	10 pc(s).
Product data	IEC: 320 V / 18 A UL: 300 V / 10 A
Packaging	Box

Creation date March 23, 2021 7:56:10 AM CET

SLH-THR5.08/16/180F 3.2SN BK BX

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

Technical data

Dimensions and weights

Depth	16.46 mm	Depth (inches)	0.648 inch
Height	43.52 mm	Height (inches)	1.713 inch
Height of lowest version	40.32 mm	Net weight	26.6 g
Width	101.6 mm	Width (inches)	4 inch

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.08	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5.08 mm
Pitch in inches (P)	0.2 inch	Outgoing elbow	180°
Number of poles	16	Number of solder pins per pole	1
Solder pin length (l)	3.2 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder eyelet hole diameter (D)	1.5 mm
Solder eyelet hole diameter tolerance (D)+ 0,1 mm		L1 in mm	86.36 mm
L1 in inches	3.4 inch	Pin series quantity	2
Volume resistance	≤5 mΩ	Can be coded	Yes
Plugging force/pole, max.	10 N	Pulling force/pole, max.	7.5 N

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	CuSn
Contact surface	tinned	Layer structure of solder connection	1...3 µm Ni / 2...4 µm Sn matt
Layer structure of plug contact	1...3 µm Ni / 2...4 µm Sn matt	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	18 A
Rated current, min. number of poles (Tu=40°C)	13 A	Rated voltage for surge voltage class / pollution degree II/2	320 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	200 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV	Short-time withstand current resistance	1 x 1s with 120 A

SLH-THR5.08/16/180F 3.2SN BK BX

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

Technical data

Rated data acc. to CSA

Institute (CSA)



Certificate No. (CSA)

200039-1121690

Rated voltage (Use group B / CSA) 300 V

Rated voltage (Use group D / CSA) 300 V

Rated current (Use group B / CSA) 13 A

Rated current (Use group D / CSA) 10 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

Rated data acc. to UL 1059

Institute (cURus)



Certificate No. (cURus)

E60693

Rated voltage (Use group B / UL 1059) 300 V

Rated voltage (Use group D / UL 1059) 300 V

Rated current (Use group B / UL 1059) 10 A

Rated current (Use group D / UL 1059) 10 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

Packing

Packaging Box

VPE length 50 mm

VPE width 95 mm

VPE height 175 mm

Classifications

ETIM 6.0 EC002637

ETIM 7.0 EC002637

ECLASS 9.0 27-44-04-02

ECLASS 9.1 27-44-04-02

ECLASS 10.0 27-44-04-02

ECLASS 11.0 27-46-02-01

Important note

IPC conformity

Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Notes

- Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

Approvals

Approvals



ROHS Conform

UL File Number Search E60693

Downloads

Approval/Certificate/Document of Conformity

[Declaration of the Manufacturer](#)

Engineering Data

[STEP](#)

Creation date March 23, 2021 7:56:10 AM CET

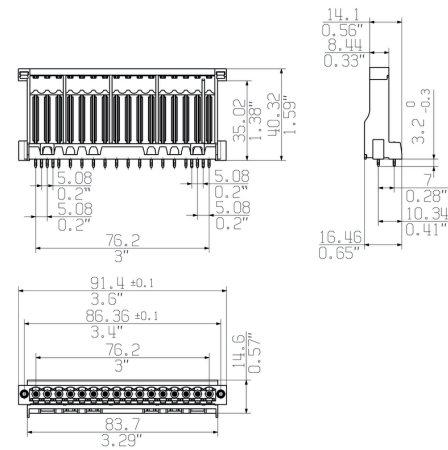
SLH-THR5.08/16/180F 3.2SN BK BX

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

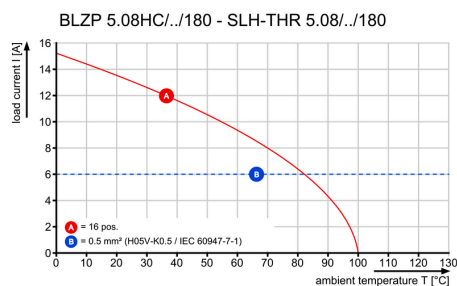
www.weidmueller.com

Drawings

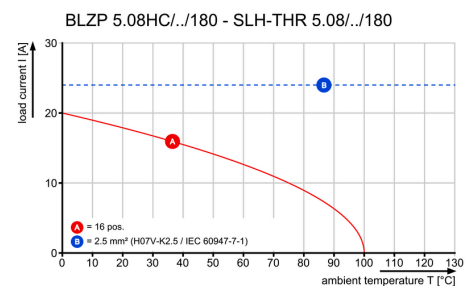
Dimensional drawing



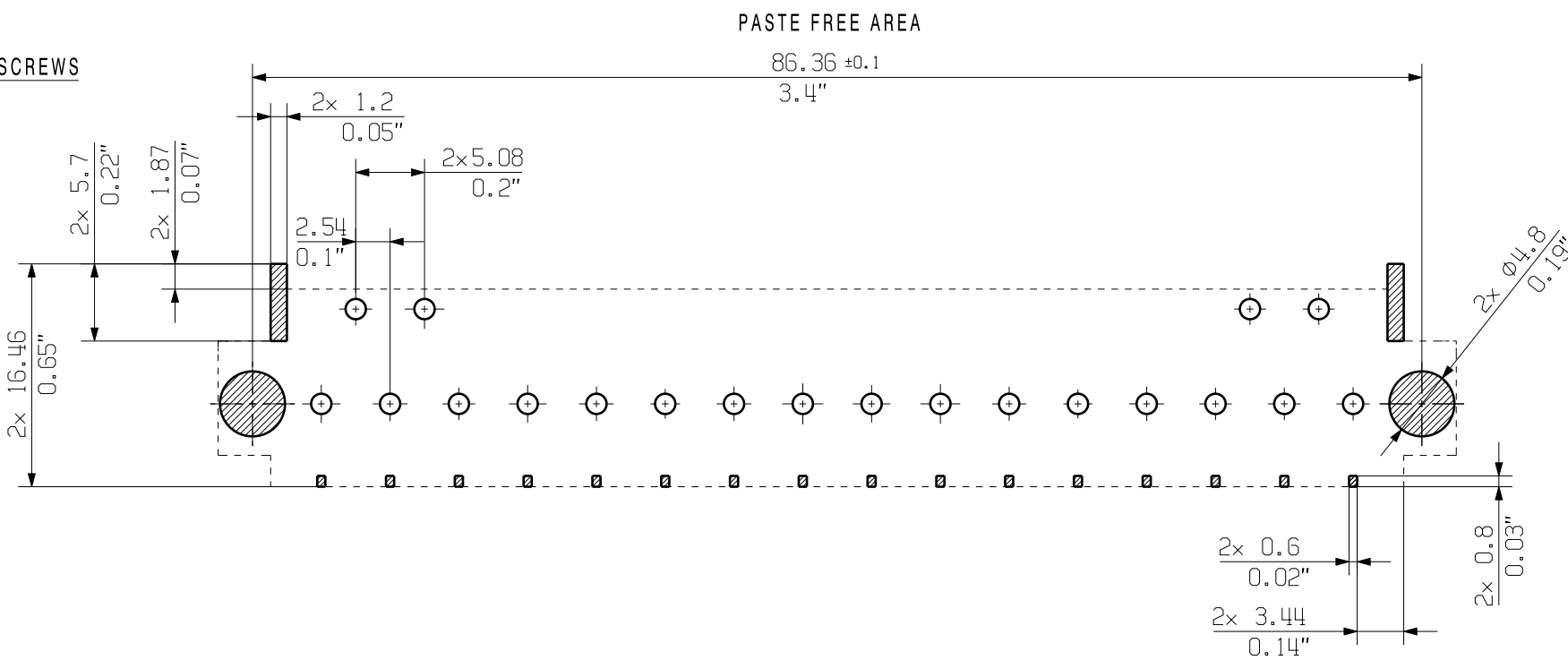
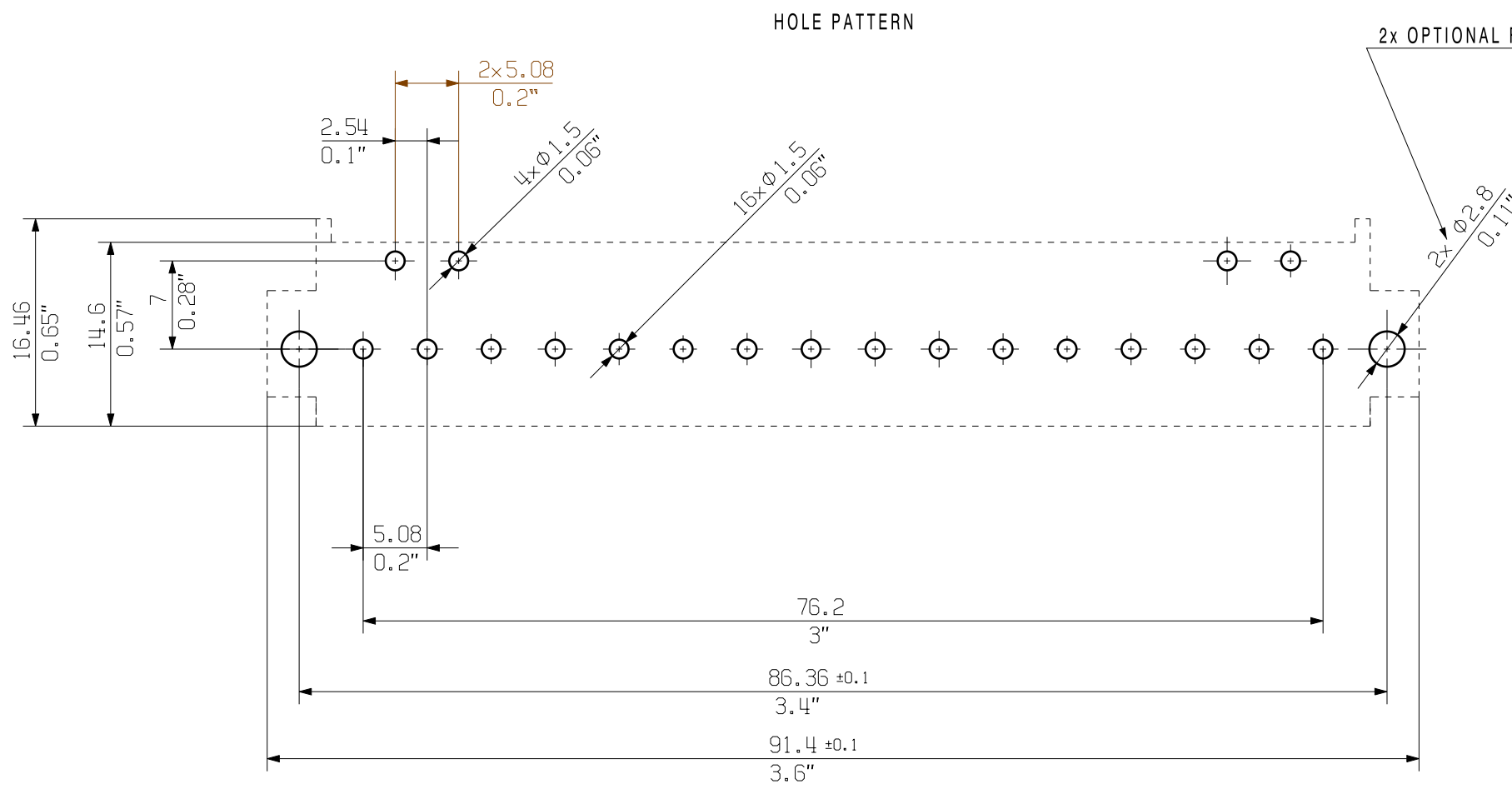
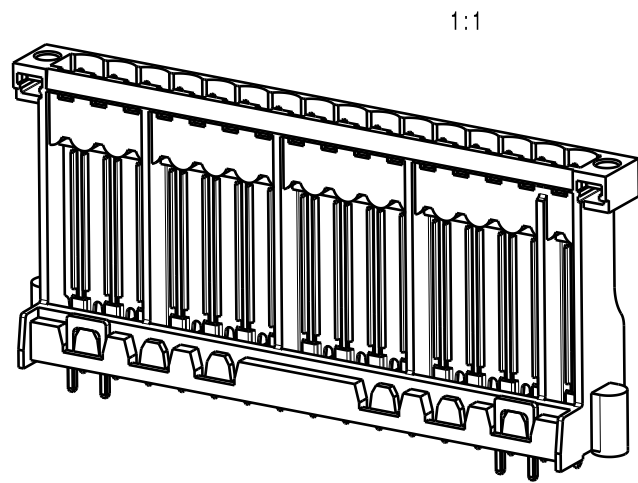
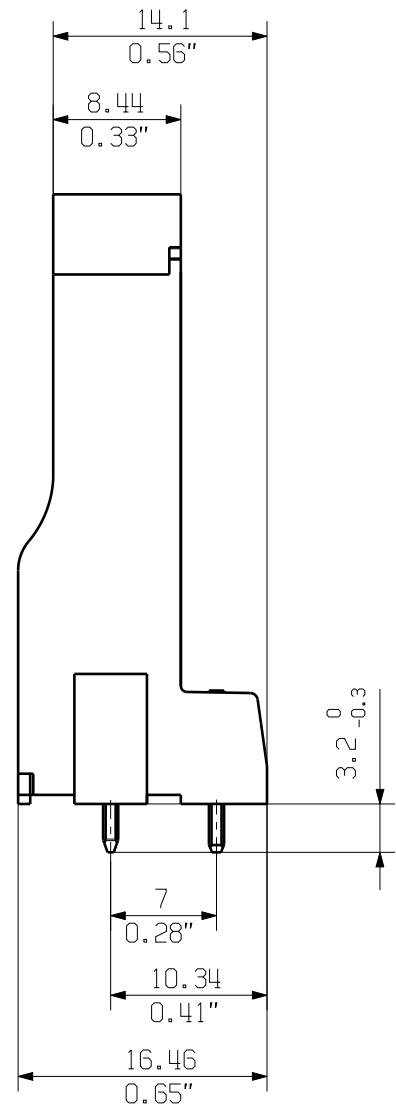
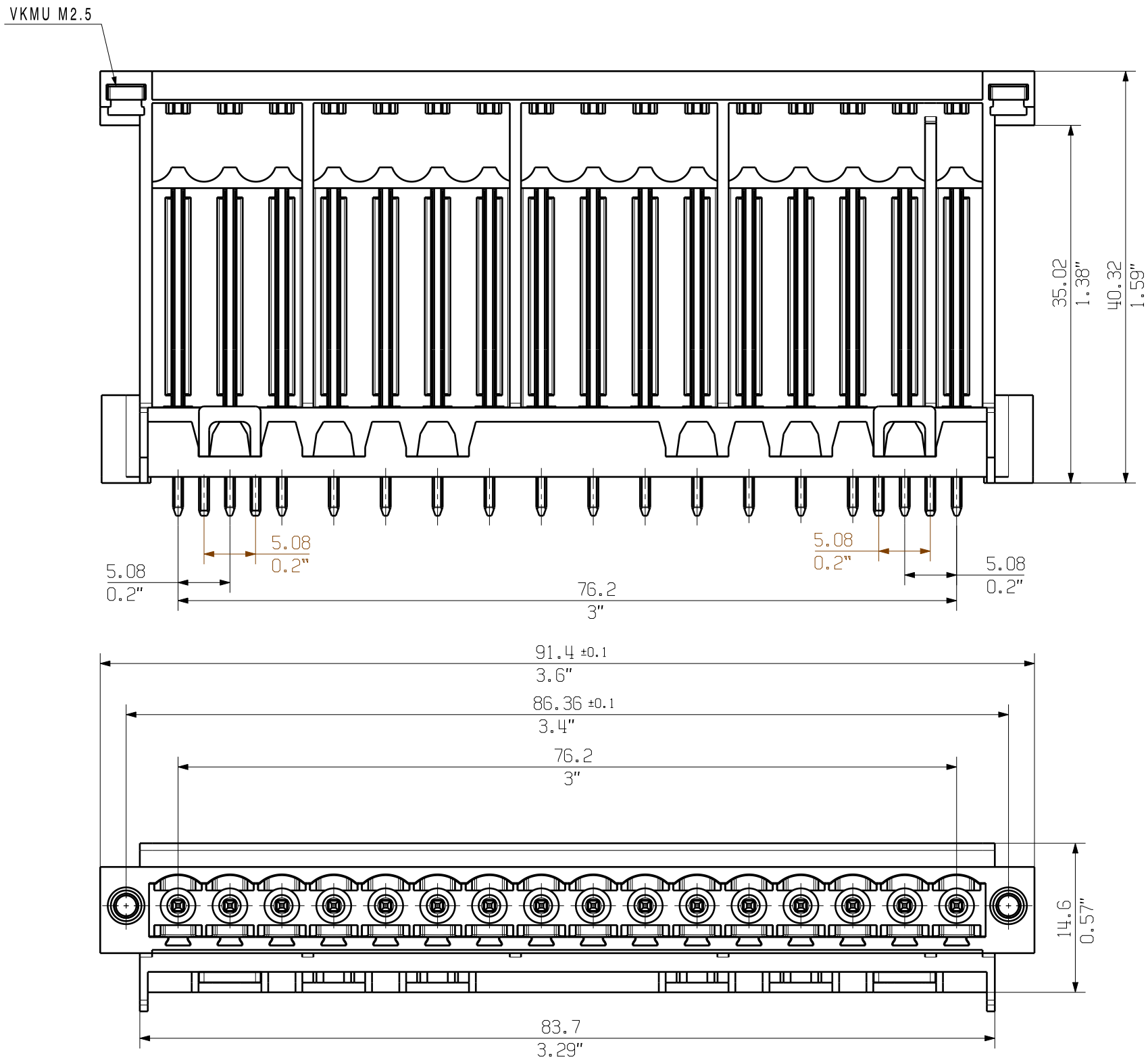
Derating curve



Derating curve



Safe power transmission
Proven properties



For the mounting of PCBs, it should be noted that the rated data relates only to the PCB components alone.
The necessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to IEC 664 / VDE 0110.
The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

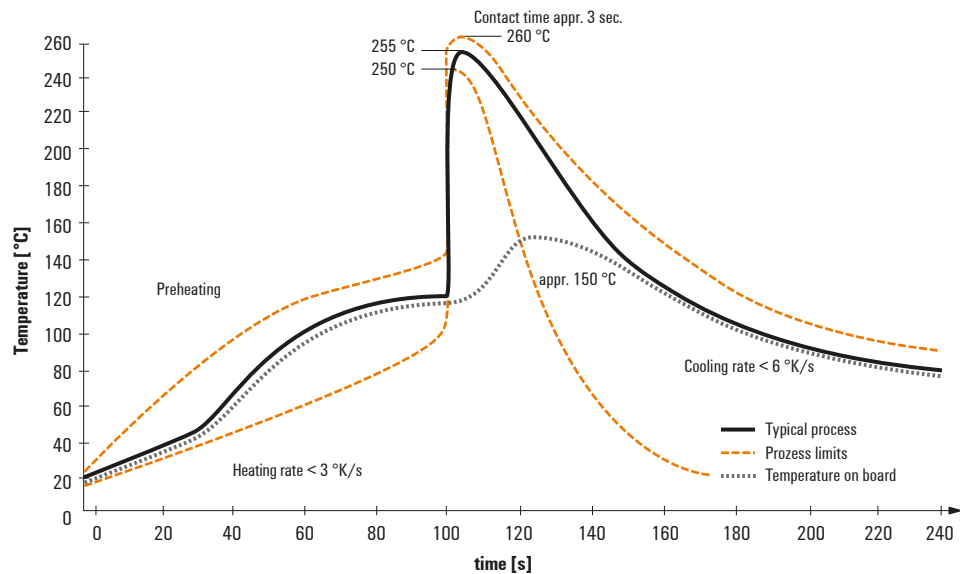
Weidmüller PCB components are tested to the DIN EN 61984 standard, and are valid for its field of application.
Provided that the components are used to the intended purpose, all requirements with respect to the occurring of electrical, mechanical, thermic and corrosive stress will be satisfied.

	METRIC TOLERANCES: X. = ±0.3 X.X = ±0.1 X.XX = ±0.05	83645/5 06.04.17 HELIS_MA 05		Cat.no.: .	
		Modification		3 51469 04	
	Scale: 2:1 Supersedes: .	Drawn	23.02.2010	HERTEL_S	SLH-THR 5.08/16/...3.2 STIFTLISTE PIN HEADER
		Responsible		HERTEL_S	
		Checked	18.04.2017	HELIS_MA	Product file: SLH-THR 5.08
		Approved		HECKERT_M	
				Sheet 01 of 01 sheets	7396

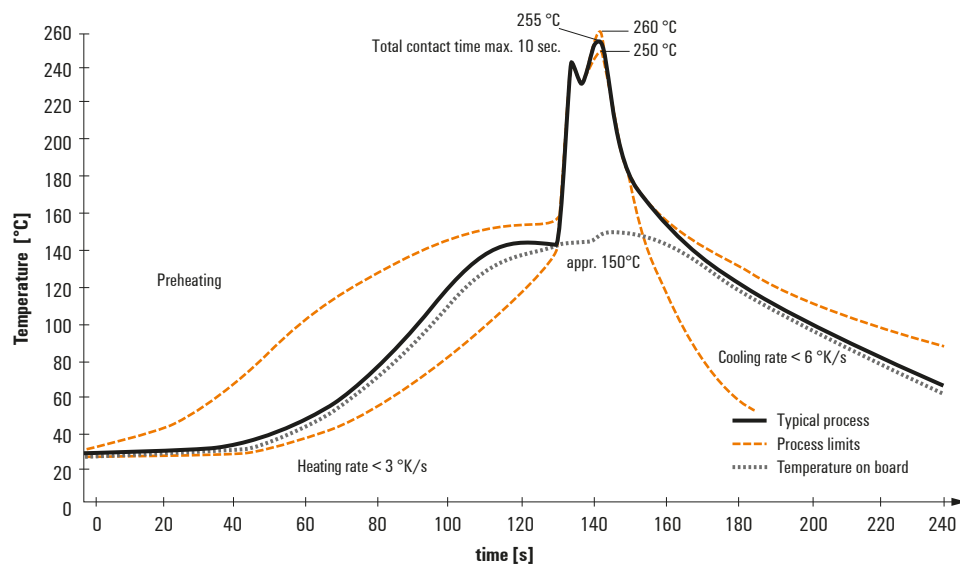
Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com

Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

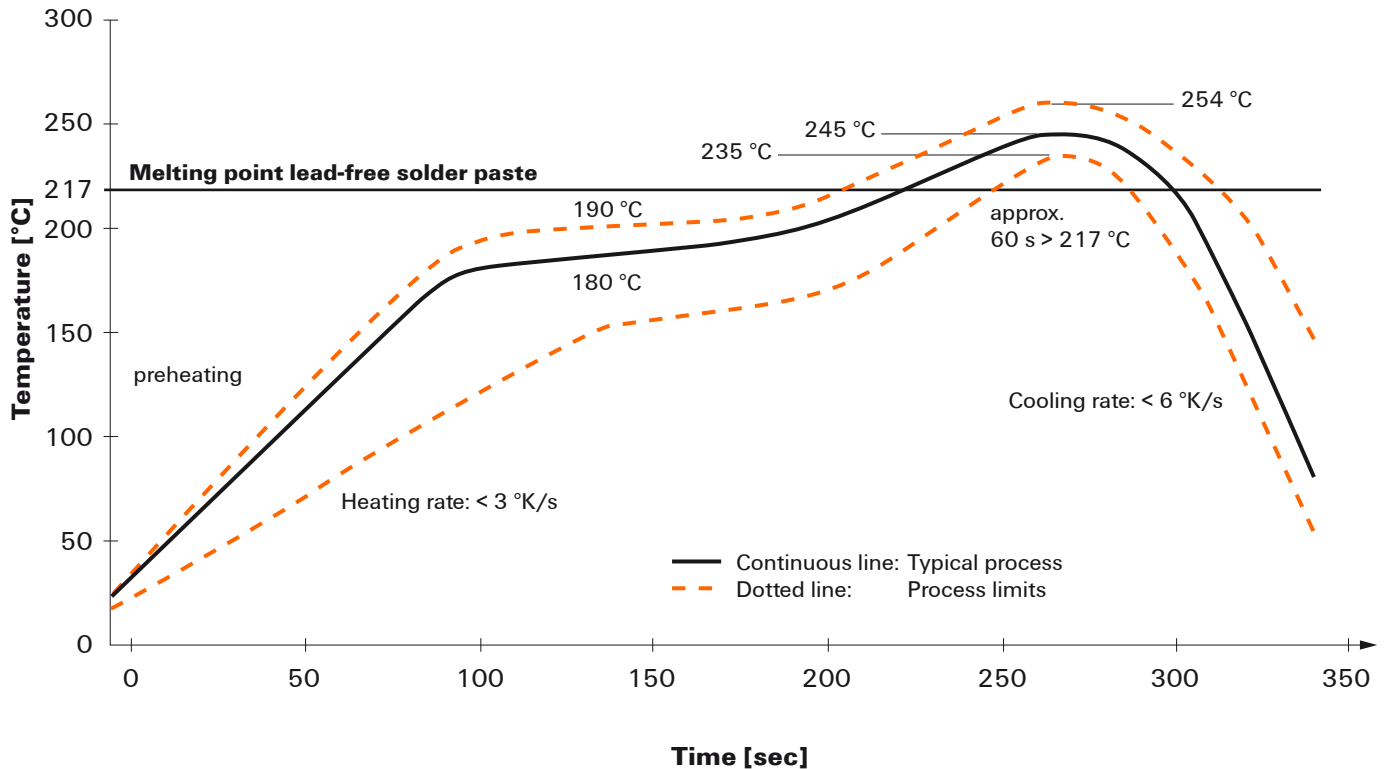
- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com



Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.